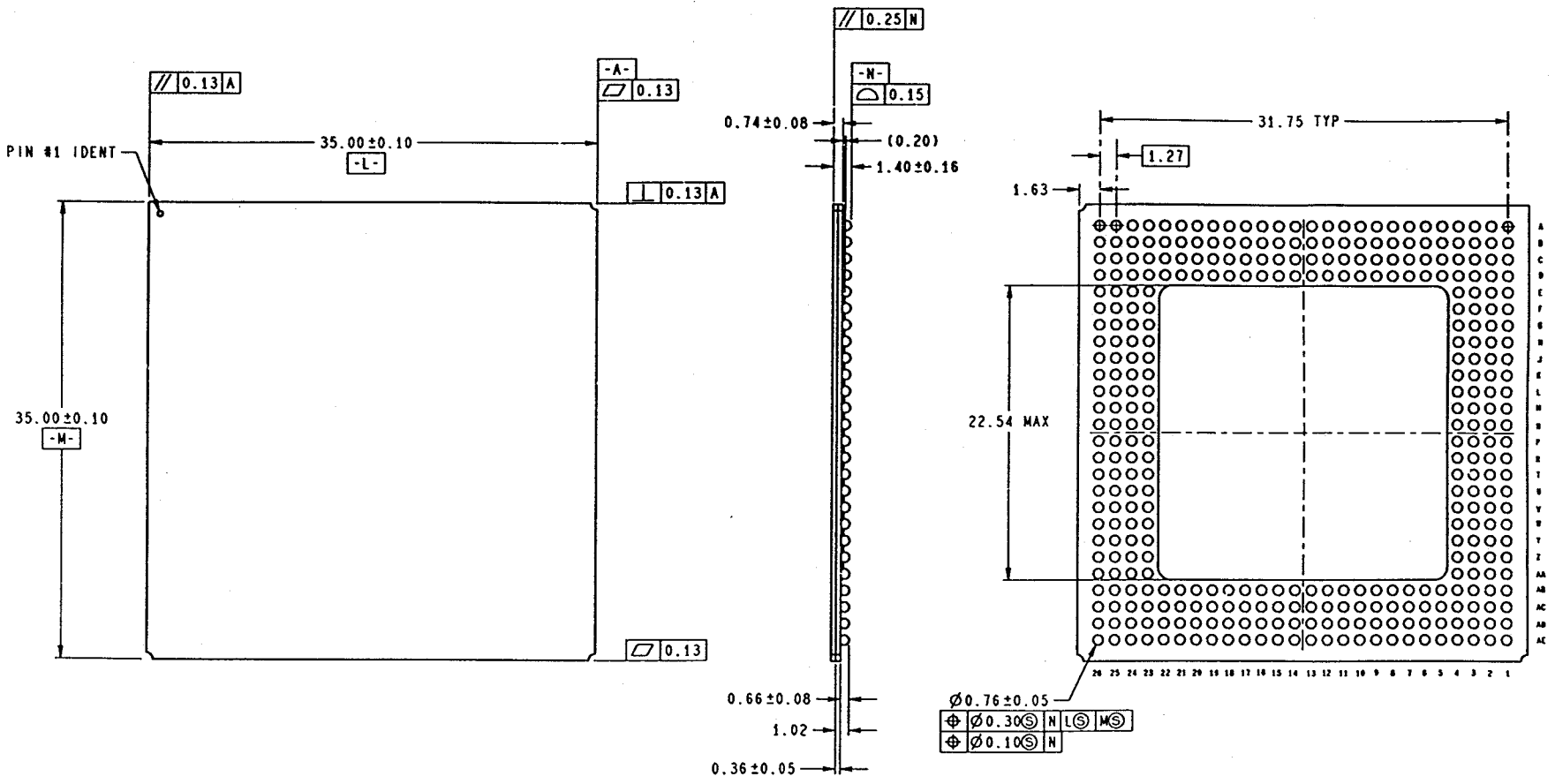


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	11084	09/06/95	DEG/32



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED 11-93.

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRW	D. E. Grady	09/06/95	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DRG. CHK.		9/12/95	SBGA, 35 X 35 X 1.40mm, 352 BALL, 1.27mm PITCH			
ENGR. CHK.	Shaw Wei Lee	9/22/95				
APPROVAL			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	MKT-UCC352A	A
			DO NOT SCALE DRAWING		SHEET 1 of 1	